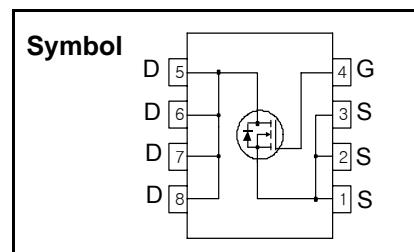


Logic N-Channel MOSFET

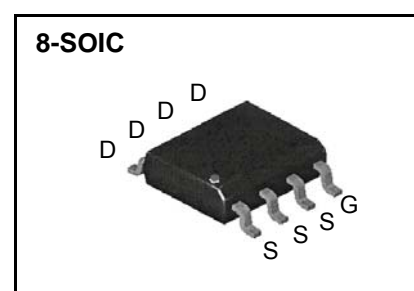
Features

- $R_{DS(on)}$ (Max 0.028 Ω)@ $V_{GS}=10V$
 $R_{DS(on)}$ (Max 0.042 Ω)@ $V_{GS}=4.5V$
- Gate Charge (Typical 18nC)
- Maximum Junction Temperature Range (150°C)
- Available in Tape and Reel



General Description

This Power MOSFET is produced using Semiwell's advanced planar stripe, DMOS technology. This latest technology has been especially designed to minimize on-state resistance, have a low gate charge with superior switching performance, and rugged avalanche characteristics. This Power MOSFET is well suited for power management circuit or DC-DC converter.



Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|----------------|--|------------|------------|
| V_{DSS} | Drain to Source Voltage | 30 | V |
| I_D | Continuous Drain Current(@ $T_A = 25^\circ C$) | 7.3 | A |
| I_{DM} | Drain Current Pulsed (Note 1) | 20 | A |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| P_D | Total Power Dissipation Single Operation ($T_A=25^\circ C$) | 2.5 | W |
| | Total Power Dissipation Single Operation ($T_A=70^\circ C$) | 1.6 | W |
| T_{STG}, T_J | Operating Junction Temperature & Storage Temperature | - 55 ~ 150 | $^\circ C$ |
| T_L | Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds. | 300 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Value | | | Units |
|-----------------|--|-------|------|------|--------------|
| | | Min. | Typ. | Max. | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 4) | - | - | 50 | $^\circ C/W$ |

SFS9410

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------------------------------------|---|--|-----|----------------|----------------|----------------------|
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 30 | - | - | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature coefficient | $I_D = 250\mu A$, referenced to $25\text{ }^\circ\text{C}$ | - | 13.5 | - | mV/ $^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS} = 24V, V_{GS} = 0V$ | - | - | 2 | μA |
| I_{GSS} | Gate-Source Leakage, Forward | $V_{GS} = 20V, V_{DS} = 0V$ | - | - | 100 | nA |
| | Gate-Source Leakage, Reverse | $V_{GS} = -20V, V_{DS} = 0V$ | - | - | -100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1.0 | - | - | V |
| $R_{DS(on)}$ | Static Drain-Source On-state Resistance | $V_{GS} = 10V, I_D = 7.3A$ $V_{GS} = 4.5V, I_D = 6.3A$ | - | 0.020 0.025 | 0.028 0.042 | Ω |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$ | - | 640 | 830 | pF |
| C_{oss} | Output Capacitance | | - | 280 | 360 | |
| C_{rss} | Reverse Transfer Capacitance | | - | 95 | 120 | |
| Dynamic Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD} = 25V, I_D = 1A, R_G = 50\Omega$ $V_{GS} = 10V$ (Note 2,3) | - | 9 | 16 | ns |
| t_r | Rise Time | | - | 16 | 30 | |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 100 | 185 | |
| t_f | Fall Time | | - | 40 | 60 | |
| Q_g | Total Gate Charge | $V_{DS} = 15V, V_{GS} = 10V, I_D = 2A$ (Note 2,3) | - | 18 | 23 | nC |
| Q_{gs} | Gate-Source Charge | | - | 1.5 | - | |
| Q_{gd} | Gate-Drain Charge(Miller Charge) | | - | 5 | - | |

Source-Drain Diode Ratings and Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit. |
|----------|---|------------------------------------|------|------|------|-------|
| I_S | Continuous Source Diode Forward Current | | - | - | 2.2 | A |
| V_{SD} | Diode Forward Voltage | $I_S = 2.2A, V_{GS} = 0V$ (Note 2) | - | - | 1.1 | V |

※ NOTES

1. Repeatability rating : pulse width limited by junction temperature
2. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
3. Essentially independent of operating temperature.
4. Surface mounted on 1 inch^2 Cu board.



Fig 1. On-State Characteristics

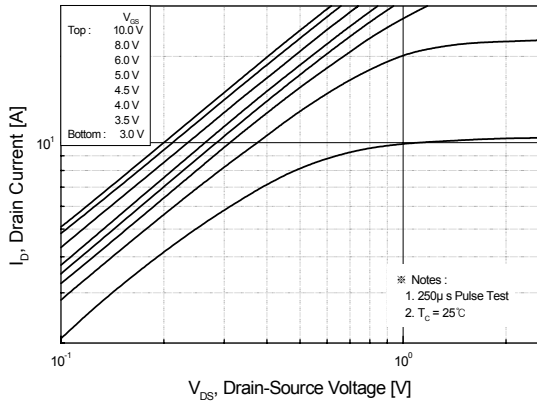


Fig 2. Transfer Characteristics

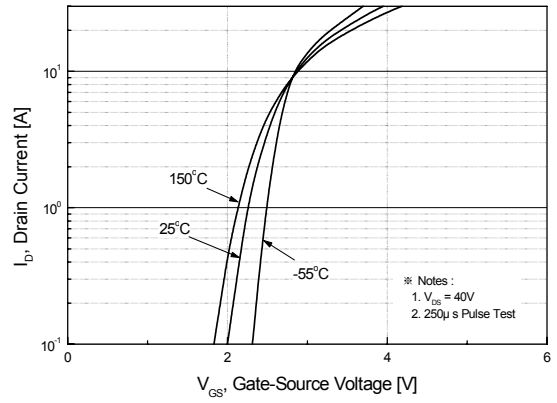


Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage

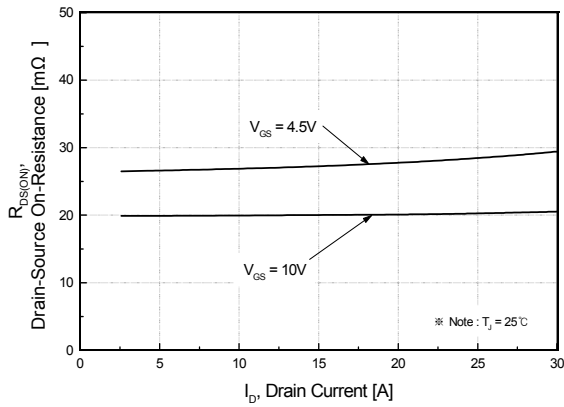


Fig 4. On State Current vs. Allowable Case Temperature

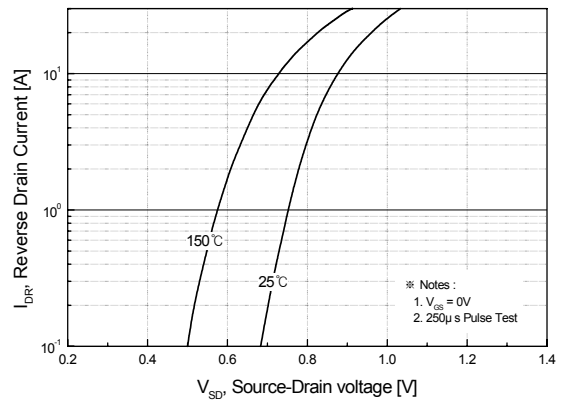


Fig 5. Capacitance Characteristics

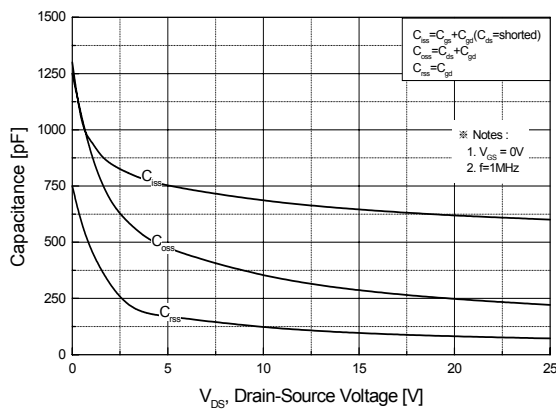
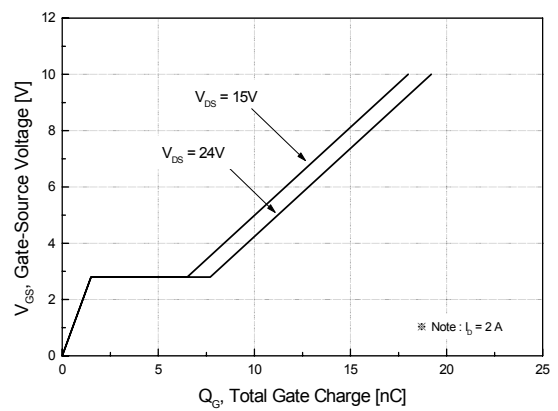


Fig 6. Gate Charge Characteristics



SFS9410

Fig 7. Breakdown Voltage Variation vs. Junction Temperature

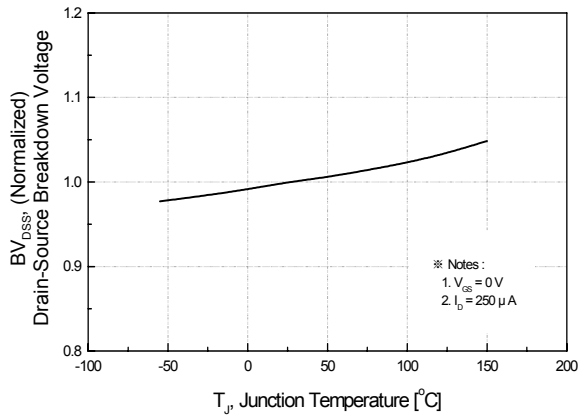


Fig 8. On-Resistance Variation vs. Junction Temperature

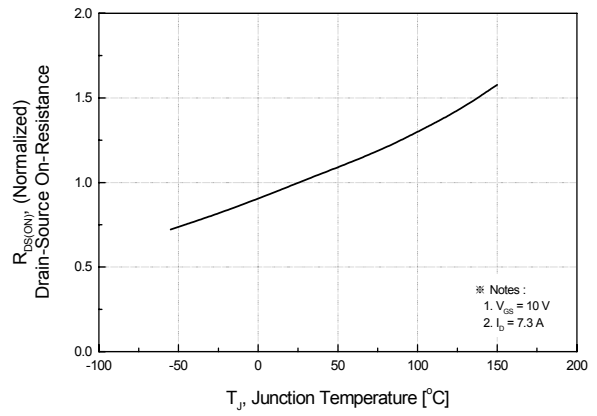


Fig 9. Normalized Transient Thermal Response Curve

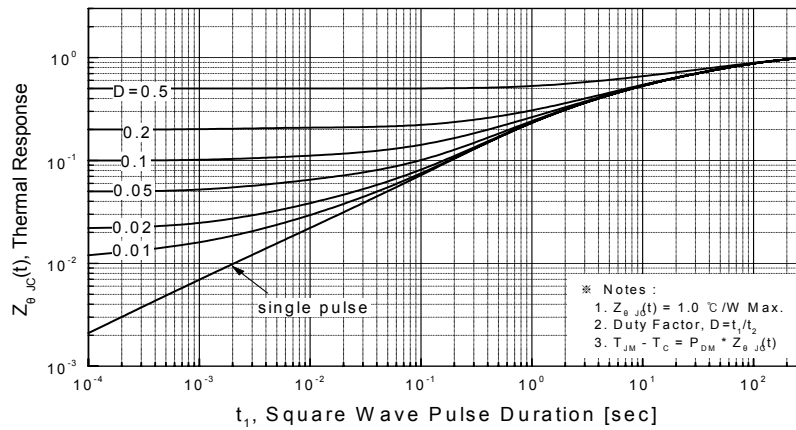


Fig. 10. Gate Charge Test Circuit & Waveforms

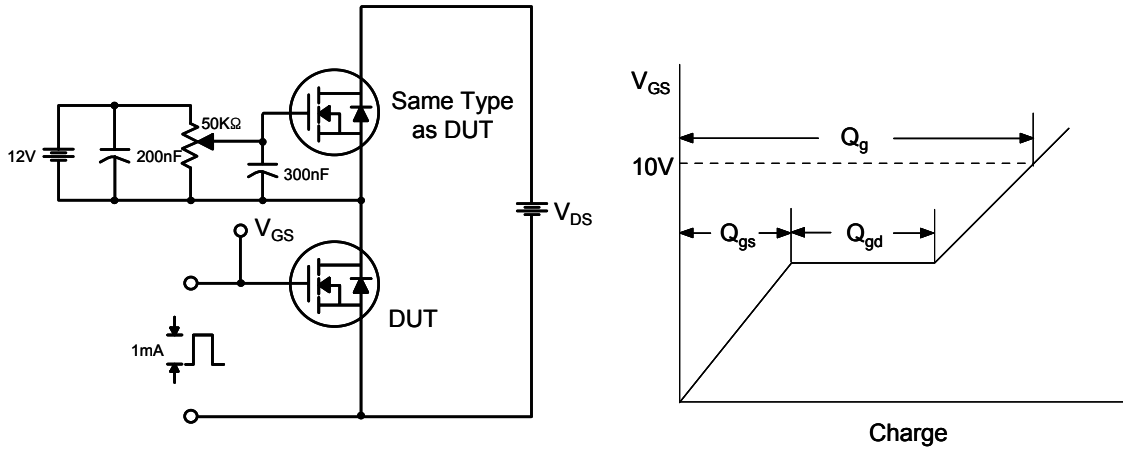
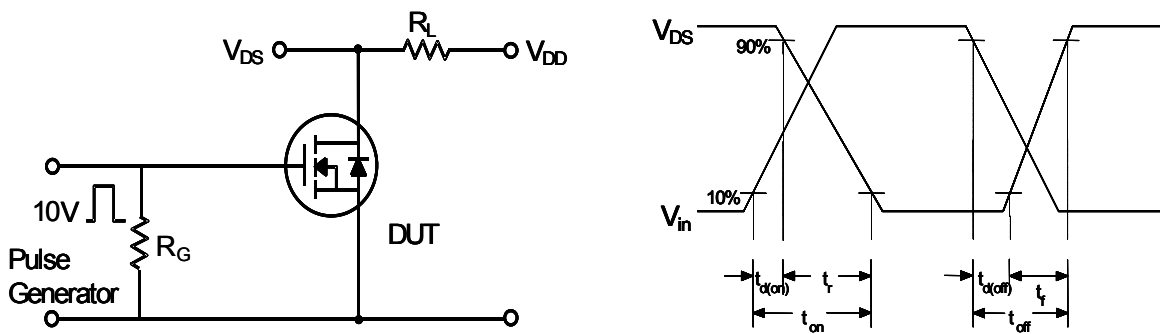


Fig. 11. Switching Time Test Circuit & Waveforms



SFS9410

8-SOIC Package Dimension

| Dim. | mm | | | Inch | | |
|------|----------|-------|-------|-------|-------|-------|
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 1.35 | 1.55 | 1.75 | 0.053 | 0.061 | 0.069 |
| B | 0.1 | 0.175 | 0.25 | 0.004 | 0.007 | 0.010 |
| C | 0.38 | 0.445 | 0.510 | 0.015 | 0.018 | 0.020 |
| D | 0.19 | 0.22 | 0.25 | 0.007 | 0.009 | 0.010 |
| E | 4.8 | 4.9 | 5 | 0.189 | 0.193 | 0.197 |
| F | 3.8 | 3.9 | 4 | 0.150 | 0.154 | 0.157 |
| G | 1.27 BSC | | | | | |
| H | 5.8 | 6 | 6.2 | 0.228 | 0.236 | 0.244 |
| I | 0.5 | 0.715 | 0.93 | 0.020 | 0.028 | 0.037 |
| J | 0' | 4' | 8' | 0' | 4' | 8' |
| K | 0.250 | 0.375 | 0.05 | 0.010 | 0.015 | 0.020 |

